

Enabling Effective and Easy to Access Simulation

Germany LS-DYNA Conference 2016

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*Other names and brands may be claimed as the property of others.

What is needed for YOUR success with simulation

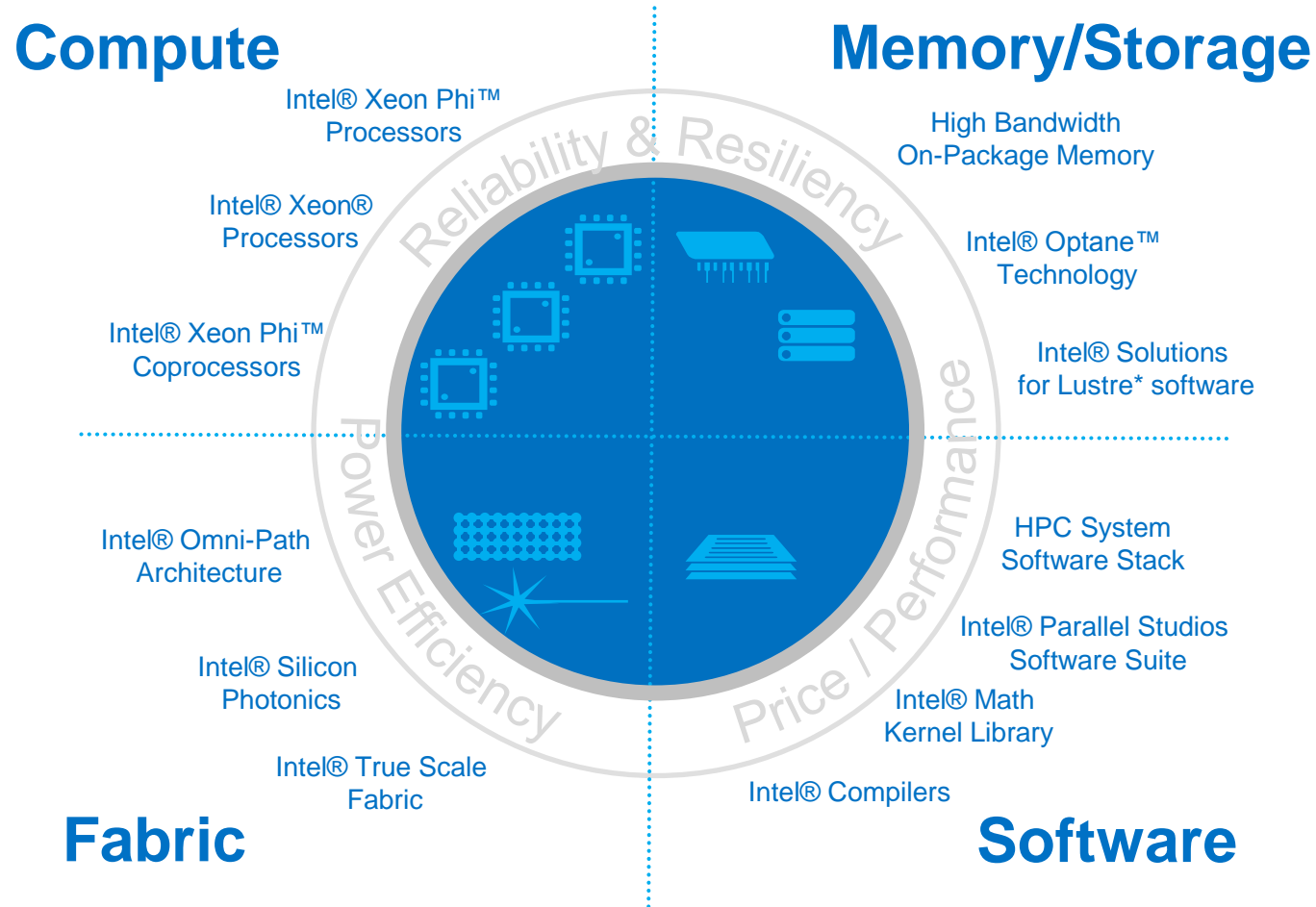
1 Compute + Provide a balanced, performant, scalable System

2 SW Ecosystem: Make sure you see performance on Applications

3 Ease of use: Accessibility & Workflows

4 Finance Dept: ROI

Compute+: Intel® Scalable System Framework



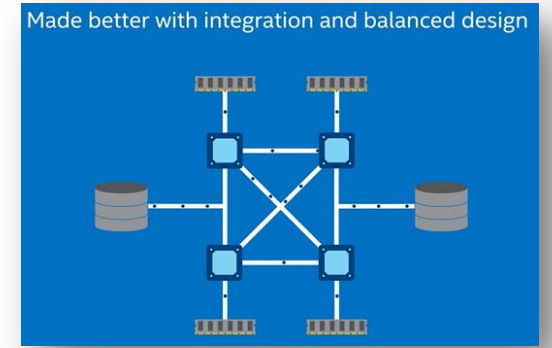
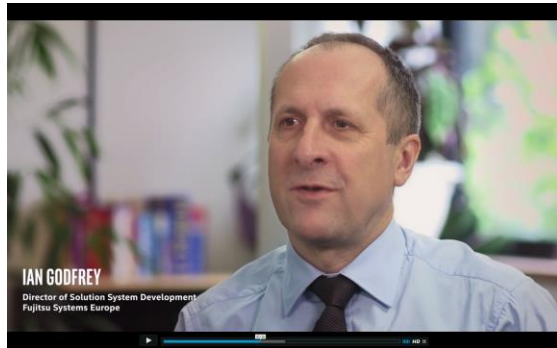
➤ Overcomes common obstacles in HPC concerning memory, fabric, storage & power

➤ Enables users to achieve performance with:

- ✓ Flexibility
- ✓ Scalability
- ✓ Balance
- ✓ Portability

Ease of USE: Solutions Ecosystem- hpc simplified

- [Intel® HPC Orchestrator](#) simplifies the installation, management, and ongoing maintenance of a high-performance computing system
- Reducing the amount of integration and validation effort required for the HPC system software stack.
- Intel® HPC Orchestrator can help accelerate your time to results and value in your HPC initiatives.



To see the full video, please follow the link:

<https://vimeopro.com/cmdvideogroup/hpc-orchestrator-v2>

So how about the ROI?

Livermore Software Tech Corp*

LS-DYNA*

"We are excited about LS-DYNA performance on the new Intel® Xeon® processor E5-2697 v4. On the Explicit workload, our benchmark testing showed up to a 32% speed up in run times, leading to faster and more productive results for our LS-DYNA users. This performance will accelerate crash results in the automotive design phase, reducing time to market."¹

Nathan A. Hallquist – Systems Software Specialist, LSTC

- Intel® AVX2, Intel® Fast Memory Access (Intel® FMA), and better memory bandwidth are delivering significant speed up in element processing and contact algorithms which are very floating point intensive.
- LS-DYNA is the leading product in the crash simulation market. It is used by the automobile, aerospace, construction, military, manufacturing, and bioengineering industries in worldwide.

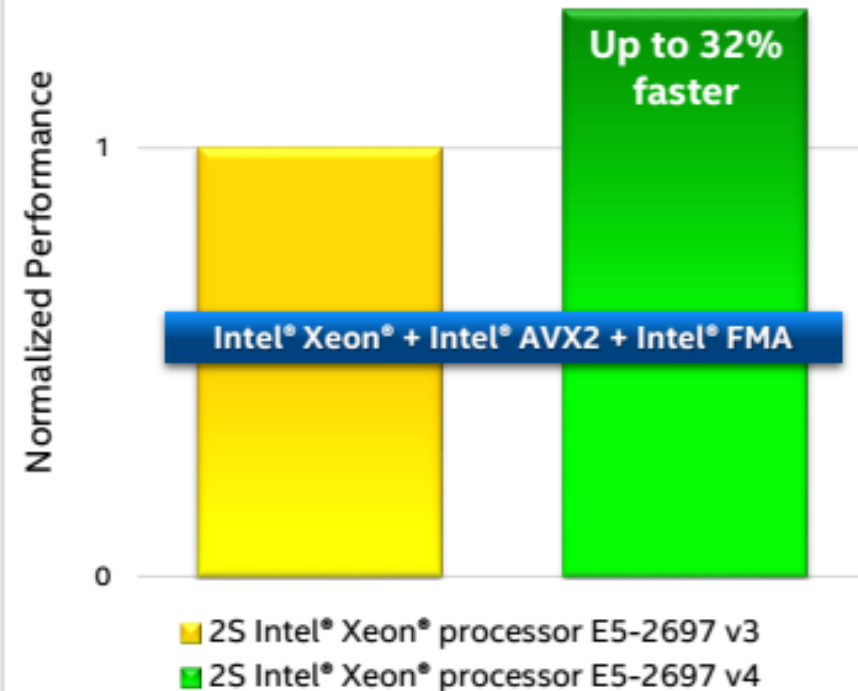
Accelerated crash results in the design phase reduces time-to-market for LS-DYNA users



www.lstc.com

Technical Computing

LSTC LS-DYNA increased performance by up to 1.32X with the 2S Intel® Xeon® processor E5-2697 v4



Workload: Topcrunch.org 3-cars model crash simulation.

1 - Testing conducted on LSTC* software comparing 2S Intel® Xeon® Processor E5-2697 v4 to 2S Intel® Xeon® Processor E5-2697 v3. Testing done by Intel. For complete testing configuration details, [SEE SLIDE 103](#). Software and workloads used in performance tests may have been optimized for performance only on Intel microprocessors. Performance tests, such as SYSmark and MobileMark, are measured using specific computer systems, components, software, operations and functions. Any change to any of those factors may cause the results to vary. You should consult other information and performance tests to assist you in fully evaluating your contemplated purchases, including the performance of that product when combined with other products. For more complete information visit <http://www.intel.com/performance>.

ROI: Advantages

Engineers

- Easy access to HPC and high end simulation
- Instant acceleration in development
- Better design capabilities
- Improving functionality

Managers

- Advantage in innovation
- Time-to-market
- Product quality
- Efficiency

Get more information

- Livermore Software Technology Corporation (LSTC). www.lstc.com
- Intel® Scalable System Framework.
www.intel.com/content/www/us/en/high-performance-computing/product-solutions.html
- Intel® Xeon® Processor E5-2600 v4 Product Family Software Solutions.
www.intel.com/content/www/us/en/processors/xeon/xeon-e5-v4-software-solutions.html

SOLUTION BRIEF



Automotive
Crash Simulations

Increasing Speeds, Reducing Costs for Growing Simulation Requirements



14. LS-DYNA Forum, Oktober 2016, Bamberg

Integrated HPC Solutions with Simplicity and Expertise

Eric Schnepf

Senior Sales Specialist HPC

Fujitsu Technology Solutions GmbH

PRIMEFLEX for HPC

Integrated HPC Solutions



Application Appliance		Reference Configuration	
Integration & Support services			
Assembly, Test & Delivery			
User workplace	HPC Gateway		
	HPC Gateway Add-ons		
Management software	Batch	Operation	Administration
System design	Head node	Compute nodes	Storage
	Interconnect	Rack & Power	Graphics



HPC Simplicity & Expertise

HPC Simplicity & Expertise

HPC Platform



Validated systems

- Optimal configuration
- Certified operation
- HPC software stack

HPC Gateway

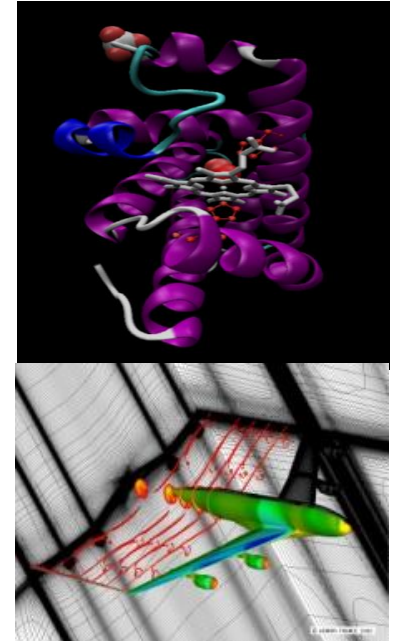


Adapted for HPC

- Application on-boarding
- Pre-defined workflow catalogue
- Collaboration & teamwork

Built-in expertise

HPC Simplicity & Expertise



Broader access

Fujitsu PRIMERGY Scale-out Systems



Platform for HPC, hosting, and hyper-converged stacks

- More computing power in less space
- Lower costs for energy due to shared power & cooling
- Optional liquid cooling for lower cooling costs and higher density



CX400

Compact server nodes with high power efficiency to realize large scale-out solutions for HPC, hosting, and hyper-converged computing at lower overall costs

Chassis



CX2550

Dual socket server node in a highly condensed half-wide, 1U form factor

Server Nodes



CX2570

Dual socket server node for ambitious HPC, analytics and visualization solutions



CX600

HPC optimized scale-out server platform based on Intel Xeon Phi x200 ("Knights Landing") technology

Chassis



CX1640

Single socket Xeon Phi server node for significant performance boost in parallel-processing

Server Node

Fujitsu PRIMERGY CX600 M1



The new platform for highly parallel computing

The FUJITSU Server PRIMERGY CX600 M1 is the perfect choice for highly parallel applications in the area of scientific research, product development and business intelligence. Up to eight server nodes per 2U and Intel® Xeon Phi™ Processors make for new levels of compute density.

Intel® Xeon Phi™ Processor

A Highly-Parallel CPU



No PCIe Bottleneck

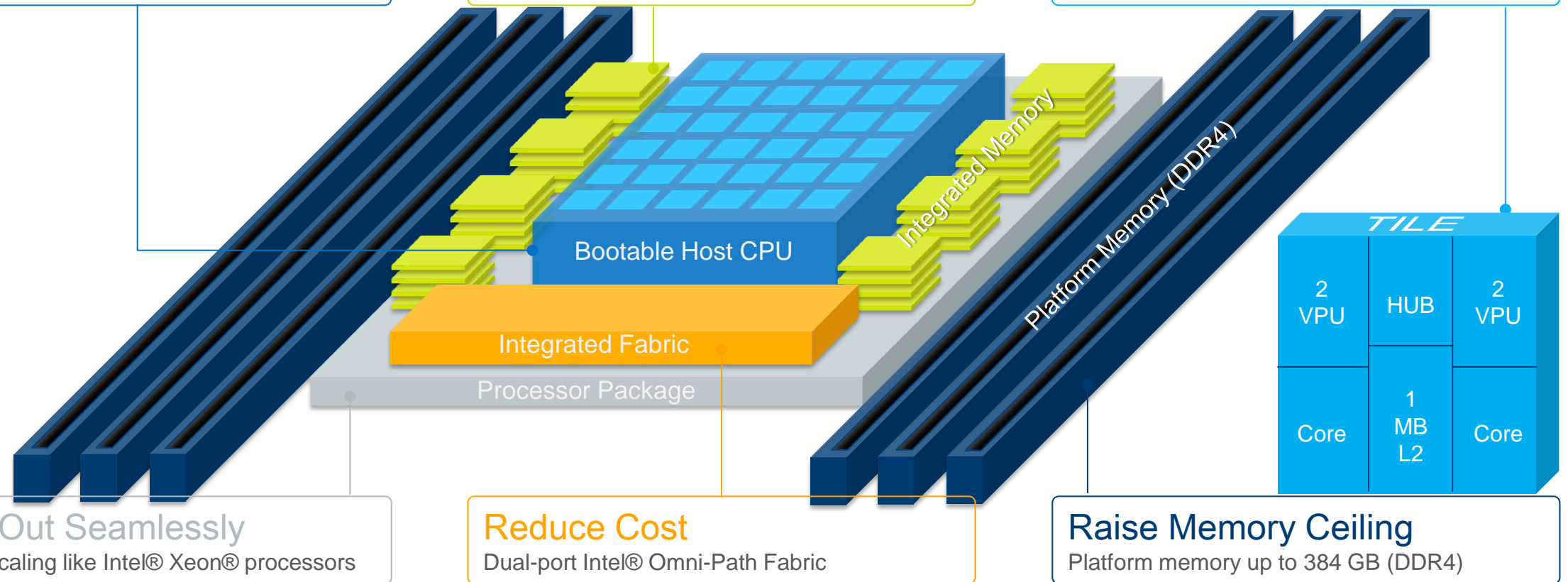
Bootable host processor

Topple Memory Wall

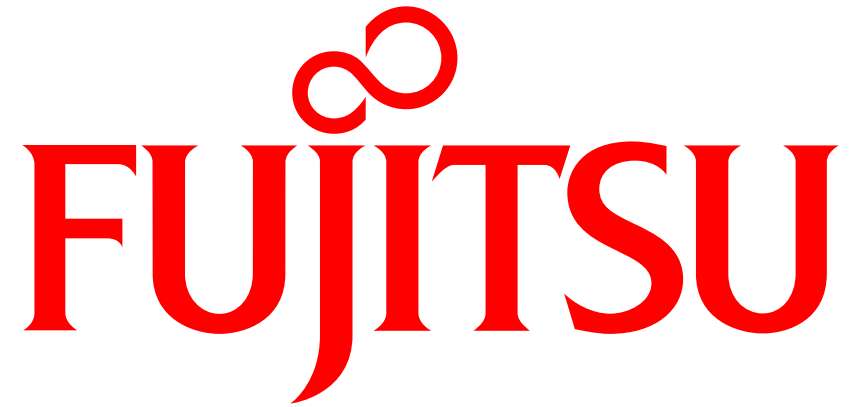
Integrated 16GB memory

Run Any x86 Workload

Intel® Xeon® processor binary-compatible



¹Reduced cost based on Intel internal estimate comparing cost of discrete networking components with the integrated fabric solution



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